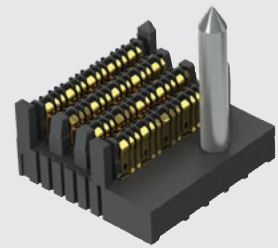


EBTM-6-12-2.0-S-VT-1



EBTM-4-08-2.0-S-VT-1-L

(2.00 mm) .0787"

ExaMAX[®] BACKPLANE SYSTEM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?EBTM or www.samtec.com?EBTF-RA

Insulator Material: Liquid Crystal Polymer

Contact Material: Copper Alloy

Plating: Sn or Au over

50 μ" (1.27 μm) Ni

Operating Temp Range: -55 °C to +85 °C

Current Rating: 4.2 A per pin

(1 pin powered)

Contact Wipe: 2.4 mm

RoHS Compliant: Yes

EBTM Mates with:

EBTF-RA

EBTF-RA Mates with:

EBTM, EBDM

PAM 4

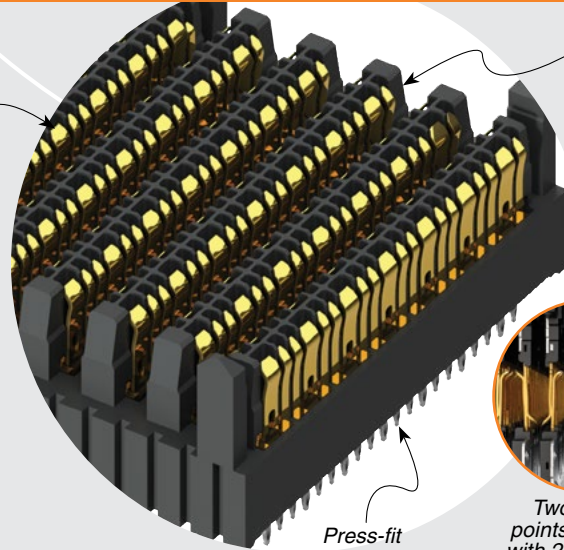
56 Gbps

APPLICATION



2.00 mm column pitch

Provides exceptionally low mating force while maintaining excellent normal force



Press-fit termination

Two reliable points of contact with 2.4 mm wipe

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



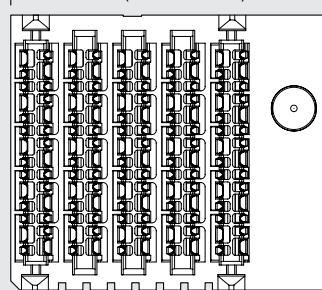
TYPE	NO. OF PAIRS PER COLUMN	COLUMNS	COLUMN PITCH
EBTM = Vertical Header	-4 = 4 Pairs	-06 -08 -10 -12 (-6 only)	-2.0 = (2.0 mm) .0787"
	-6 = 6 Pairs		
EBTF = Right-Angle Receptacle			

ALSO AVAILABLE (MOQ Required)

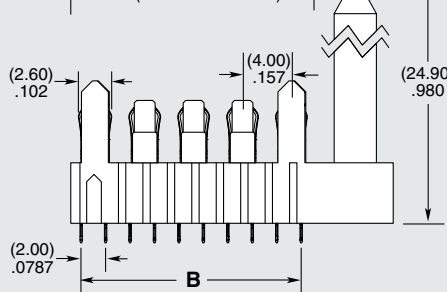
- Staging
 - Keying
- Contact Samtec.

COLUMNS	A	B	C
-06	(11.90) .469	(10.00) .394	(18.35) .722
-08	(15.90) .626	(14.00) .551	(22.35) .880
-10	(19.90) .783	(18.00) .709	(26.35) 1.037
-12	(23.90) .941	(22.00) .866	(30.35) 1.188

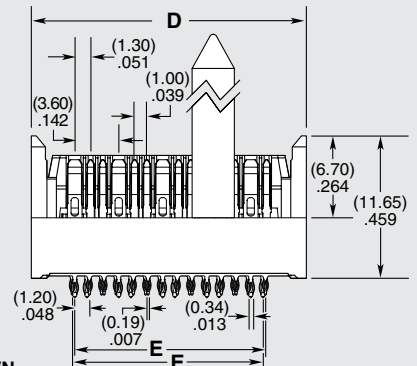
C (With Guidance)



A (Without Guidance)



NO. OF PAIRS PER COLUMN	D	E
-4	(22.50) .886	(15.60) .614
-6	(29.70) 1.169	(22.80) .898



EBTM-4-10-2.0-S-VT-1-L SHOWN

Notes:

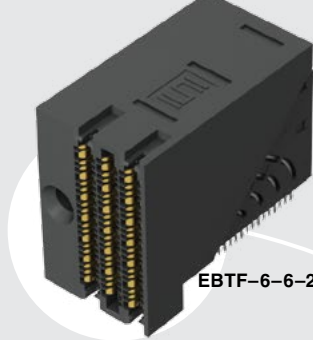
Some lengths, styles and options are non-standard, non-returnable.

ExaMAX[®] is a registered trademark of AFCI.

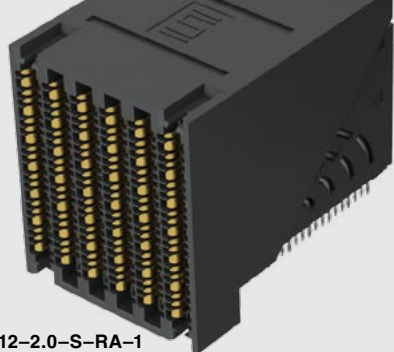
Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.



EBTF-6-6-2.0-S-RA-1-L

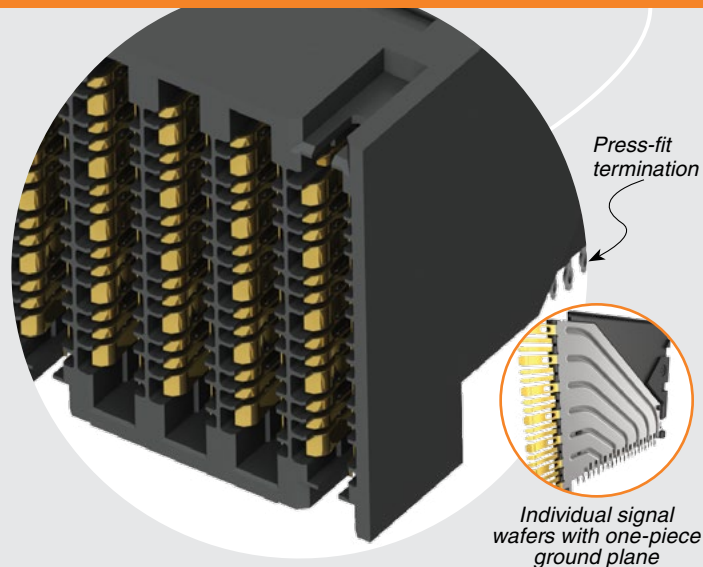
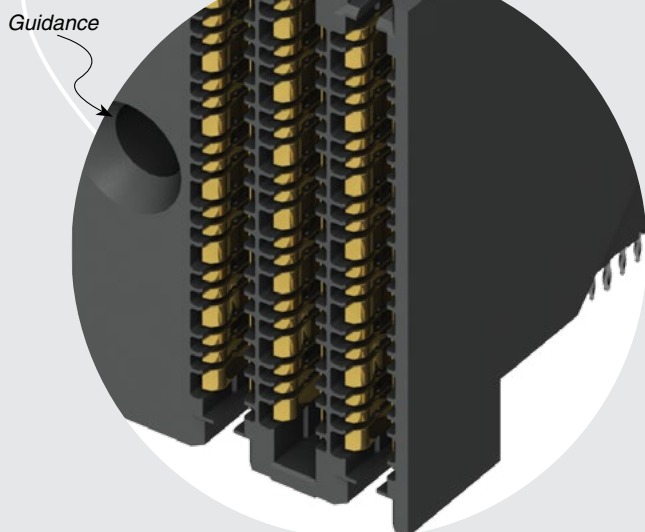


EBTF-6-12-2.0-S-RA-1



EBTF-4-10-2.0-S-RA-1

EBTM, EBTF-RA SERIES



PLATING

-S

= 30 μ" (0.76 μm)
Gold on contact area,
Matte Tin on tail

ORIENTATION

-VT

= Vertical
(EBTM only)

-RA

= Right-Angle
(EBTF-RA only)

1

GUIDANCE

(Leave Blank for no Guidance)

-L

= Left Guidance

-R

= Right Guidance

END WALLS

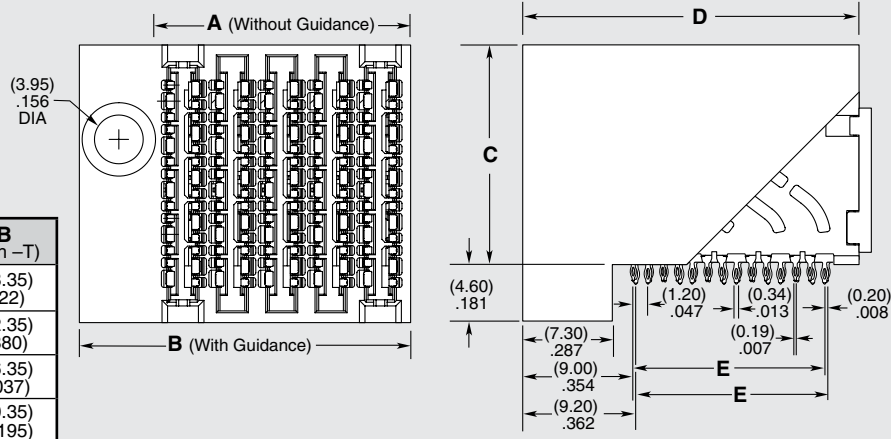
(Leave Blank for Thick End Wall)

-T

= Thin Walls
(EBTF-RA only)

NO. OF PAIRS PER COLUMN	C	D	E
-4	(17.90) .705	(28.40) 1.118	(22.80) .898
-6	(25.10) .988	(35.60) 1.402	(22.80) .898

COLUMNS	A	A (with -T)	B	B (with -T)
-06	(12.90) .506	(11.90) .469	(18.85) .742	(18.35) .722
-08	(16.90) .665	(15.90) .626	(22.85) .900	(22.35) .880
-10	(20.90) .823	(19.90) .783	(26.85) 1.057	(26.35) 1.037
-12	(24.90) .980	(23.90) .941	(30.85) 1.215	(30.35) 1.195



EBTF-4-10-2.0-S-RA-1-L SHOWN

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